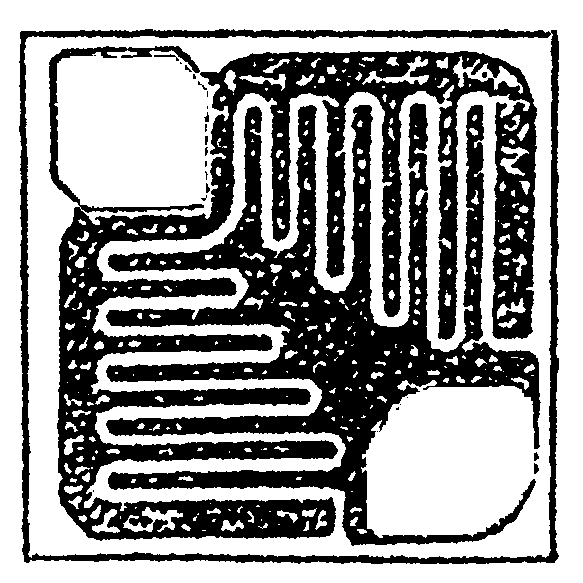
****

**Top Material: Al**

**Backside Material: Gold**

**Bond Pad Size: .004 x .004”**

**Backside Potential: Collector**

**Mask Ref:**

**APPROVED BY: JK DIE SIZE : .022” x .022” DATE: 10/4/21**

**MFG: MICROSEMI THICKNESS: .015” P/N: 2N3250**

**DG 10.1.2**

#### Rev B, 7/19/02